MARKET REPORT Q4 2026

WHERE SUPPLY IS TIGHTEST:
MEMORY, POWER, AND PASSIVES

61-week MLCC lead times
and what to do about them **p6**

EOL notices from
10 manufacturers **p23**

Industrial MicroSD
made by ASC Global **p20**

electronica 2026 EDITION
HALL B5
STAND 578



BOOK A QUALIFIED MEETING AT HALL B5, STAND 578

WIN THE FLORIDA EXPERIENCE

No purchase necessary. See page 5.

ALL-EXPENSES-PAID
TRIP FOR TWO

ASC GLOBAL

HARD TO FIND? NOT FOR US.
WE SOURCE IT, MATCH IT, OR MAKE IT.

ASC GLOBAL

electronica

HARD TO FIND? NOT FOR US.

WE SOURCE IT, MATCH IT, OR MAKE IT.

Global Shortage and Allocation Sourcing

Lab-Tested and Traceable

Industrial MicroSD Manufacturing

Drop-In Replacements for OEM Cards

EOL and Obsolescence Solutions

Pin-to-Pin Alternatives and Custom Manufacturing

BOOTH B5.578



BRING YOUR HARDEST-TO-FIND PART NUMBERS

TRACEABLE SOURCING.
REAL AVAILABILITY.
AS 9120 | ISO 9001 | AS 6081

www.ascglobal.com

WE BUY EXCESS INVENTORY IN 24 HOURS OR LESS

Send your list: quote@ascglobal.com | +1 954 718-2950

A Note from Our CEO

Dear customer and partner,

Every quarter, buyers tell us the same thing: “I can’t find it.” This quarter it’s truer than ever. AI is the fastest-growing source of demand in electronics, and memory, power, and passive components are feeling it first. Lead times and prices keep moving.

This report shows where supply is tightest and what to do about it. My advice is simple. Review your bill of materials now, not when a line stops. Ask for confirmed quantities, qualify alternatives, and plan further out than feels necessary.

That is what our team does every day. We source it, match it, or make it, and every open-market part goes through our lab. If you’re at electronica, visit us in Hall B5, Stand 578. If not, send us your part numbers.

One more thing. Book a qualified meeting at our stand, and you are entered to win the Florida Experience: an all-expenses-paid trip for you and a guest to our headquarters, one-on-one time with me, and a tour of Fort Lauderdale. No purchase necessary; details on page 5.

One call. One source.

Mario Gaete

Mario Gaete
CEO, ASC Global

Table of Contents

ASC Global delivers lead times, allocation, and EOL notices for the quarter ahead. Our sourcing, testing, and data teams compiled this report from our own market activity and public industry sources.

6 **Where Supply Is Tightest**
- Memory, Power, and Passives
- Allocation Watch (p. 9)

10 **Lead Times & Pricing**
- Six Product Categories, Factory and Open Market
- Price Action Tracker (p. 19)

21 **Manufacturing & End of Life**
- Manufacturing Capabilities
- End of Life Reports (p. 23)
- Authorized & Sourced Lines (p. 25)

26 **Planning for the Memory Exit**
- DDR3 and DDR4 Supply Risk
- How to Calculate Your Last-Time Buy

29 **Test Report Analysis**
- Failure Rates by Device and Manufacturer
- Test Types & Results
- Hot Commodities (p. 32)
- Where to Buy (p. 33)

34 **Market Updates & Earnings**
- Product & Manufacturer Updates
- Earnings Recap (p. 38)
- Industry Updates (p. 40)
- Earnings Signals (p. 42)

43 **Industries We Cover**
- Long-lifecycle, high-reliability programs
- Aerospace, automotive, data centers, medical, and more

ASC GLOBAL



ELECTRONICA 2026 · MUNICH · HALL B5, STAND 578 · NOV 10 TO 13

BOOK A QUALIFIED MEETING. WIN THE FLORIDA EXPERIENCE.

Win an all-expenses-paid trip for two to ASC Global's Florida headquarters. Meet our CEO one-on-one and see Fort Lauderdale.

THE GRAND PRIZE

- **All-expenses-paid trip for you and a guest to our Florida headquarters**
- **A one-on-one meeting with our CEO**
- **Sun, sand, and a tour of Fort Lauderdale**



HOW TO ENTER

1 Book a meeting
Before or during the show: online, by email, by phone, or at Hall B5, Stand 578.

2 Meet our team
Talk with us at the stand about a current sourcing need.

3 Get your entry
Your rep confirms your entry in the meeting. You get a confirmation email after the show.

The winner will be drawn and notified by email by November 30, 2026.

No purchase necessary. Open to business customers and prospects aged 18 or over who hold a qualified meeting with ASC Global during electronica, November 10 to 13, 2026, booked before or during the show. A qualified meeting is a scheduled meeting between an ASC Global representative and a buyer, engineer, or decision-maker about a current sourcing need. The ASC Global representative confirms entries at the meeting, and entrants receive a confirmation email after the show. One winner will be selected at random and notified by email by November 30, 2026. The prize covers the winner and one guest, is non-transferable, and has no cash value. Not open to competitors, ASC Global employees, or their families. Winners must confirm that their employer permits them to accept the prize. Entry data is used only to run the drawing and follow up on your meeting, in line with applicable data-protection law. Void where prohibited. Full official rules are available at the stand or from quote@ascglobal.com.

BOOK YOUR MEETING TODAY

www.ascglobal.com · quote@ascglobal.com · +1 954 718 2950
or visit us at Hall B5, Stand 578

WHERE SUPPLY IS TIGHTEST: MEMORY, POWER, AND PASSIVES

AI is the fastest-growing source of demand in electronics. Here is where supply is tightest heading into 2027, and how to keep your production on schedule.

AI Is Driving a New Wave of Component Demand

GPUs and high-bandwidth memory get the headlines. Every AI server also runs on large amounts of memory, power conversion, and passive components. Manufacturers are investing in new capacity, but demand is growing faster than new factories can come online.

This demand reaches well beyond data centers. Buyers in automotive, medical, industrial, and consumer markets use many of the same parts, so longer lead times and allocation reach their procurement too. The impact ripples through several critical application categories:

- **Automation Systems:** Factory automation, robotics, and industrial control frameworks.
- **Communications Equipment:** Networking hardware, enterprise communication infrastructure, and field telemetry tools.
- **Embedded Electronics:** Microcontrollers, specialized processors, and peripheral chipsets integrated directly into end products.

Three Component Categories to Watch

1. Memory and Storage

Samsung, SK hynix, and Micron are prioritizing HBM, server DDR5, and enterprise SSDs. TrendForce expects conventional DRAM contract prices to rise another 10 to 15% in Q4 2026, and NAND flash 15 to 20%. That follows a 90 to 95% jump in DRAM contract prices in Q1 alone.

Enterprise SSDs are the fastest-growing NAND market, with bit demand forecast to grow more than 80% this year. As new capacity goes to these products, legacy DDR4, eMMC, and commodity NAND see tighter supply. See page 26 for how to plan for the DDR3 and DDR4 exit.

2. Power and Analog Components

AI racks are moving from 12 V and 48 V power distribution toward 800 VDC. That shift multiplies demand for PMICs, multiphase controllers, power MOSFETs, and SiC and GaN devices.

Infineon reports its AI power business is on allocation and is signing multi-year capacity reservations with AI customers. Analog Devices told customers in July that lead times on part of its portfolio are stretching to six months. Texas Instruments, Analog Devices, onsemi, and Renesas have all issued price notices in 2026.

BOOK A QUALIFIED MEETING. WIN THE FLORIDA EXPERIENCE. No purchase necessary · Rules on page 5

3. Capacitors and Passives

An AI server uses more than ten times as many MLCCs as a conventional server. Some Samsung Electro-Mechanics MLCCs now list 61-week factory lead times at a major distributor, up from 39 to 49 weeks in September. Its 47 µF high-capacitance MLCC rose about 23% in price between August and October.

Murata is shifting capacity to AI server parts and discontinuing some consumer and automotive MLCCs. Demand for polymer tantalum and polymer aluminum capacitors is rising the same way.

The Numbers Behind the Demand

61 weeks
Factory lead time listed for some Samsung Electro-Mechanics MLCCs, October 2026

10x
MLCCs in an AI server compared with a conventional server

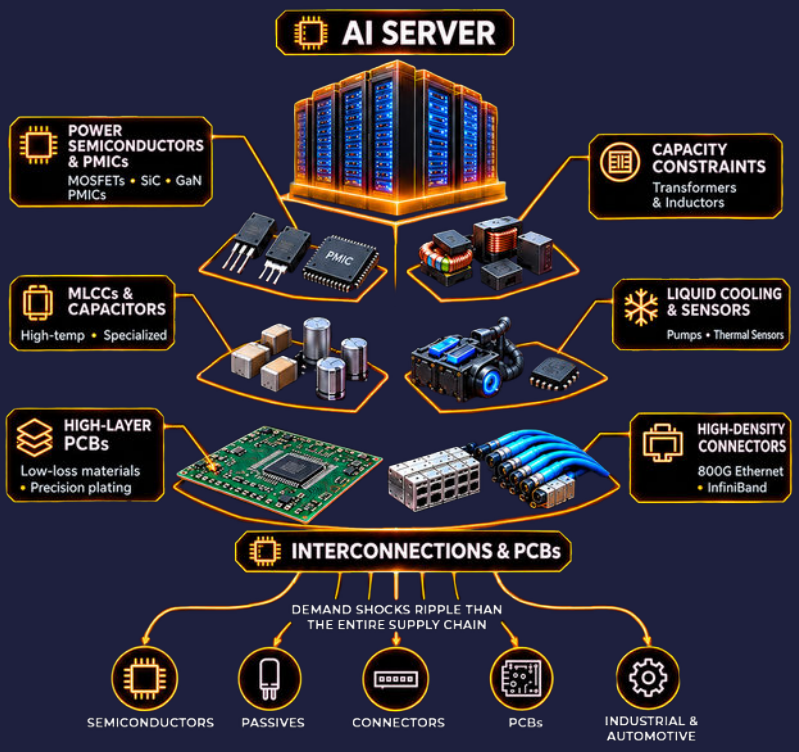
+23%
Price rise on a 47 µF high-capacitance MLCC, August to October 2026

+10 to 15%
Q4 2026 conventional DRAM contract price forecast

+15 to 20%
Q4 2026 NAND flash contract price forecast

6 months
Lead times on part of the Analog Devices portfolio, per its July notice

Beyond the GPU: Where Demand Reaches Next



- **Power delivery:** High-performance processors drive demand for power semiconductors and PMICs. As foundries add AI chip output, mature-node capacity for analog parts stays tight.
- **Thermal and passives:** Dense racks need specialized MLCCs, high-temperature capacitors, and thermal sensors. Industrial and automotive buyers order from the same production lines.
- **Interconnects and PCBs:** High-speed links need high-layer-count boards and high-density connectors, the same parts 800G networking gear uses.

The Quieter Risk: Targeted Discontinuations

Manufacturers are trimming portfolios to put capacity where margins are highest. A mature part can stay essential to your production line while becoming a low priority for the company that makes it.

This quarter's EOL notices show the pattern. STMicroelectronics is dropping the TESEO-LIV3F GNSS module for slow sales, with no replacement listed. Analog Devices is ending tin-lead versions of the LT1580IT after its packaging partner closed the line. Murata is retiring low-margin MLCCs. When a notice lands, the buying window is short.

How Buyers Can Respond

01 Verify allocations early. Ask suppliers for confirmed quantities, delivery dates, and quote validity on DDR5, enterprise SSD and NAND, PMICs, MOSFETs, high-capacitance MLCCs, and polymer capacitors. Treat a quoted lead time as the shortest possible wait, not a delivery promise.

02 Build risk-based safety stock. Rank your BOM by how much a missing part would cost you and how likely it is to go short. Hold buffer stock only for parts that can stop a line, and require traceability, date codes, and test reports on every lot.

03 Qualify alternatives now. Pre-qualify form-fit-function and pin-to-pin alternatives before you need them. Check electrical specifications, temperature range, package, footprint, and firmware. For memory, replacing the full module is often easier than substituting chips.

04 Audit your BOM and plan further out. Flag single-source, EOL, and mature-node parts, plus anything with a lead time over 26 weeks. Share 12-month forecasts with your suppliers, and place orders before announced price changes take effect, such as Renesas on January 1, 2027.

How ASC Global Helps

When the authorized channel cannot deliver, we can. ASC Global sources allocated memory, power, and passive components through a network of more than 2,000 manufacturers and suppliers. Every open-market part goes through our lab, with AS 6081, AS 9120, and ISO 9001 certified processes.

We also run BOM risk reviews, find pin-to-pin alternatives for EOL parts, set up scheduled deliveries and VMI programs, and manufacture industrial MicroSD cards and custom SSDs.

Bring your hardest-to-find part numbers to Hall B5, Stand 578, or send them to quote@ascglobal.com.

Sources: TrendForce (September 30, 2026); Newspim and Financial Post, citing TrendForce and distributor listings (October 22 and 24, 2026); Analog Devices customer notice (July 3, 2026); Infineon fiscal 2026 results; ASC Global market data.



Allocation Watch

Supply alerts by category, Q4 2026. Most items come from distributor or customer reports, often a single account, and are not confirmed by the manufacturer. Verify part by part before acting.

DRAM / RDIMM

CHANNEL-REPORTED

Micron reportedly raised 96GB and 128GB RDIMM prices 15 to 25% in September, with further increases expected in October. Memory makers reportedly told at least one major non-hyperscale account to expect only about 10 to 20% of its 2027 board-memory demand.

Legacy DDR3 / DDR4

CHANNEL-REPORTED

Micron DDR3 book pricing is reportedly up about 50%, including MT41K256M16TW-107 (see Hot Commodities, p. 32), with DDR4 and LPDDR4 up about 10%. At least one networking account was reportedly told to expect no industrial DDR4 allocation, prompting pre-buys of 50,000 to 100,000+ units.

Analog

CHANNEL-REPORTED

ADI op-amp, DAC, and voltage-reference families (for example AD5545BRUZ, AD8672ARMZ, ADR435ARMZ) are reported at 60 to 70 weeks, well beyond the six-month figure in ADI's July notice. TI TMCS current sensors are reported in line-down shortage, and some suppliers are reported to apply new pricing to open orders.

FPGAs

CHANNEL-REPORTED

Altera lead times are reported near 60 weeks, with forecasts requested through 2028. Lattice is reported at 32 to 40+ weeks for industrial parts, and one industrial account cited 18+ months on Xilinx 7-series devices.

Passives

CHANNEL-REPORTED

Samsung Electro-Mechanics reportedly cut September allocations by about 20% ahead of its October 1 price rise, and Yageo high-capacitance MLCCs are reportedly allocated by bidding. Yageo AC-series automotive resistors are reported up 25% from September.

Power & Discretes

CHANNEL-REPORTED

Vishay issued a decommit on MOSFET SIB452DK-T1-GE3 tied to fab overbooking, pushing new deliveries into late 2027. Diodes Inc. high-runner automotive parts are reported beyond 40 weeks at one Tier 1, and Skyworks is reportedly closing a diode line for 2027.

Continuity Risks

PUBLIC SOURCE

Nexperia's China entities remain legally and operationally separate from the group, so verify country of origin, date code, and customer acceptance before committing substitute stock. Infineon plans to sell its NOR Flash and F-RAM business to Winbond, targeting an H2 2027 close. Start PCN monitoring and second-source evaluation for affected designs.

Data Center Hardware

CHANNEL-REPORTED

Seagate 24TB channel pricing is reported up from about $700 to $1,150 since July. Optical transceivers for NVIDIA Rubin builds are reported at 441-day lead times (1.6T), and some Mellanox transceivers beyond 50 weeks. One embedded account cited roughly 50-week Intel server CPU lead times, while AMD cut some EPYC quoted lead times from 20 to 12 weeks.

Hit by an allocation alert? Send us the part numbers.
We check availability, traceability, and alternatives. Hall B5, Stand 578.
quote@ascglobal.com
+1 954 718 2950

Sources: company disclosures, TrendForce, and distributor channel intelligence. CHANNEL-REPORTED items are not verified by the manufacturer.

Lead-Time Report

The following insights stem from thorough research of ASC Global's marketing team combined with the expertise of all our departments. The information is designed to provide guidance and should be approached as such.
ASC Global helps buyers plan around this volatility. For current availability, send your part numbers to quote@ascglobal.com.

↔ Stable ↑ Increasing ↓ Decreasing EOL End-of-life

Analog | **Power** | **Logic & Digital** | **Passives** | **Electromechanical** | **Memory**

Analog

Data as of November 2, 2026

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
PMIC	Nordic Semiconductor	18-20	↔	↔	↔	↔
	NXP	22-24	↔	↑	↔	↑
	Texas Instruments	24-48	↑	↑	↑	↑
	Analog Devices	16-40	↑	↑	↑	↑
Power Converters/ Controllers	onsemi	14-26	↑	↑	↔	↑
	MPS	24-52	↑	↔	↔	↑
	Texas Instruments	20-48	↑	↑	↔	↑
	Analog Devices	16-40	↑	↑	↔	↑
Gate Drivers	Power Integrations	14-18	↔	↑	↔	↔
	ROHM	16-20	↑	↔	↔	↔
	Silergy	16-20	↔	↔	↔	↔
	Allegro MicroSystems	20-36	↑	↑	↔	↔

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
LED Drivers	Silergy	14-16	↑	↑	↔	↔
	MPS	24-52	↑	↔	↔	↔
	ROHM	16-26	↑	↔	↔	↔
	STMicroelectronics	30-52	↑	↑	↔	↔
Timing	Onsemi	22-32	↔	↑	↔	↑
	Microchip	7-12	↔	↑	↔	↔
	Renesas	20-26	↑	↑	↑	↑
Interface	NXP	10-20	↔	↑	↔	↑
	Renesas	12-14	↑	↑	↔	↑
Amplifiers and Data Converters	Microchip	4-10	↔	↑	↔	↔
	Onsemi	10-16	↔	↑	↔	↔
	Renesas	14-16	↑	↑	↔	↑
	STMicroelectronics	28-30	↑	↑	↔	↑
	Texas Instruments	20-50	↑	↑	↔	↑
	Analog Devices	16-40	↑	↑	↔	↑

AI servers need more power management per rack, and hyperscalers are buying PMICs, multiphase controllers, and signal-chain parts in volume. Analog Devices told customers in July that lead times on part of its portfolio are stretching to six months. Texas Instruments, Analog Devices, onsemi, and Renesas have all issued price notices this year, some with no single effective date. Confirm pricing part by part and order at least two quarters ahead.

HARD-TO-GET PARTS. EASY TO TRUST.

Memory, power, and passives from a certified distributor. AS 9120 | ISO 9001 | AS 6081

Memory and Storage

- DDR5 / DDR4
- DDR3 / DDR3L (EOL)
- Enterprise SSD and NAND

Power and Analog

- Power management ICs
- Power MOSFETs and power stages
- Analog and interface ICs

Passives

- High-capacitance MLCCs
- Polymer tantalum capacitors
- Polymer aluminum capacitors

Power

Data as of November 2, 2026

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
IGBT's	Microchip	12-26	↔	↔	↔	↔
	Littelfuse	21-60	↑	↑	↔	↑
	onsemi	12-52	↑	↑	↔	↑
	Infineon	14-52	↑	↑	↔	↑
High Voltage MOSFET's	Littelfuse	17-52	↔	↑	↔	↑
	onsemi	10-52	↑	↑	↔	↑
	MCC	24-38	↔	↔	↔	↑
Low Voltage MOSFET's	Infineon	12-52	↑	↑	↔	↑
	Vishay	12-52	↑	↑	↔	↑
	STMicroelectronics	14-26	↑	↑	↔	↑
Wide Bandgap MOSFET's	Littelfuse	27-35	↑	↔	↔	↔
	Infineon	16-52	↑	↑	↔	↑
	onsemi	14-52	↑	↑	↔	↑
	STMicroelectronics	20-36	↑	↔	↔	↑
GaN	Infineon	12-16	↔	↑	↔	↑
	onsemi	20-40	↔	↑	↔	↑
	STMicroelectronics	21-48	↔	↔	↔	↔
	Texas Instruments	14-20	↔	↑	↔	↑
Rectifiers	Diodes Incorporated	26-52	↔	↔	↔	↑
	onsemi	20-25	↑	↑	↔	↑
	STMicroelectronics	20-22	↑	↔	↔	↔
	Vishay	14-16	↑	↑	↔	↑

AI racks are moving to 800 VDC power distribution, which pulls SiC and GaN MOSFETs, high-voltage MOSFETs, and power modules into data center designs. Infineon reports its AI power business is on allocation and is signing multi-year capacity reservations with AI customers. EV, renewable energy, and industrial demand compete for the same capacity. Expect long lead times on IGBTs and wide bandgap parts, and pricing set at shipment.

Passives

Data as of November 2, 2026

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
Capacitors	Kyocera	14-16	↔	↑	↔	↑
	Abracon	20-22	↔	↑	↔	↑
	EATON	10-20	↔	↑	↔	↑
Resistors	Panasonic	18-20	↑	↑	↔	↑
	ROHM	8-10	↔	↔	↔	↑
	Samsung Electro-Mechanics	44-46	↔	↔	↔	↑
	Vishay	20-22	↑	↔	↔	↑
Inductors / Transformers	EATON	16-18	↔	↑	↔	↑
	Vishay	10-12	↔	↑	↔	↑
	Panasonic	23-25	↔	↔	↔	↔
Surface Mount General Capacitors	TDK	26-36	↑	↔	↔	↑
	Samsung Electro-Mechanics	30-48	↑	↑	↔	↑
	Kyocera	24-30	↑	↑	↔	↑
Aluminum Electrolytic	NIC Components	28-38	↑	↑	↔	↑
	Nichicon	30-36	↑	↑	↔	↑
	Panasonic	36-46	↑	↑	↔	↑
Filters	TDK	30-32	↑	↑	↔	↑
	NIC Components	20-24	↑	↑	↔	↑
	TAIYO YUDEN	20-26	↑	↑	↔	↑
Polymer Tantalum / Polymer Aluminum	KEMET	18-32	↑	↑	↔	↑
	TDK	20-50	↑	↑	↔	↑
	Panasonic	16-30	↑	↑	↔	↑

High-capacitance MLCCs are the tightest passive category. Samsung Electro-Mechanics raised Q4 prices on AI-server MLCCs by 10 to 20%, and some of its MLCCs now list 61-week factory lead times at a major distributor, up from 39 to 49 weeks in September. Murata is moving capacity to AI server parts and discontinuing some consumer and automotive MLCCs. Polymer tantalum and polymer aluminum capacitors face the same pull.

Memory

Data as of November 2, 2026

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
NAND Flash	Alliance Memory	16-24	↑	↑	↓	↑
	GigaDevice	26-30	↑	↑	↓	↑
	Macronix	30-52	↑	↑	↓	↑
NOR Flash	Alliance Memory	12-20	↑	↑	↓	↑
	GigaDevice	12-26	↑	↑	↓	↑
	Infineon	20-26	↑	↑	↓	↑
Memory Modules	Centon	26-52	↑	↑	↓	↑
	Kingston	6-12	↑	↑	↓	↑
	ADATA	26-52	↑	↑	↓	↑
	SMART Modular	26-52	↑	↑	↓	↑
SRAM	Renesas	20-24	↔	↔	↓	↑
	ONSEMI	20-52	↔	↑	↓	↑
	Microchip	4-11	↑	↑	↓	↑
	Alliance Memory	8-30	↑	↔	↓	↑
EEPROM	STMicro	12-20	↑	↑	↓	↑
	ONSEMI	20-52	↑	↑	↓	↑
	ROHM	12-26	↔	↔	↔	↔
	Microchip	4-28	↑	↑	↓	↑
NOR Flash	Microchip	15-30	↑	↑	↓	↑
	Renesas	26-42	↑	↑	↓	↑
	Infineon	20-26	↑	↑	↓	↑
	Alliance Memory	12-20	↑	↑	↓	↑

Western Digital.
Authorized Reseller

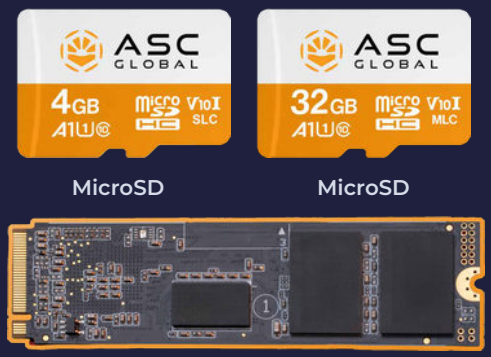
We have availability on
• HDDs • SSDs
• NAS Devices
• Flash Drives



ASC GLOBAL

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
eMMC	Micron	26-52	↑	↑	↓	↑
	Alliance Memory	26-52	↑	↑	↓	↑
	Kingston	24-26	↑	↑	↓	↑
	Greenliant	26-52	↑	↑	↓	↑
PC (Commodity) DRAM	Kingston	24-26	↑	↑	↓	↑
	Alliance Memory	8-52	↑	↑	↓	↑
Solid State Drives	Kingston	24-26	↑	↑	↓	↑
	Greenliant	26-52	↑	↑	↓	↑
	ADATA	26-52	↑	↑	↓	↑

Conventional DRAM contract prices are expected to rise another 10 to 15% in Q4 2026 and NAND flash 15 to 20%, after record increases earlier this year. Samsung, SK hynix, and Micron are steering capacity to HBM, server DDR5, and enterprise SSDs. That leaves DDR4, eMMC, and commodity NAND with less supply. Secure allocations early and validate module compatibility before you need the parts.



MicroSD MicroSD

Custom SSD

MADE BY ASC

INDUSTRIAL MICROSD & CUSTOM SSDs

Storage that stays the same for the life of your product.

- **EOL storage** — Drop-in replacements for discontinued cards and drives.
- **Allocation and lead times** — Supply from our own production, not the allocation queue.
- **Silent BOM changes** — A controlled, locked BOM for the life of your program.
- **Harsh environments** — MicroSD rated -40°C to +85°C. SSDs specified for temperature, shock, and vibration.

See page 20 for Industrial MicroSD and page 28 for Custom SSDs

Free engineering samples · quote@ascglobal.com

Logic & Digital

Data as of November 2, 2026

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
8 Bit MCU	Renesas	14-18	↑	↔	↔	↔
	Microchip	4-12	↔	↔	↔	↔
	STMicro	40-52	↑	↔	↔	↑
	NXP	16-39	↑	↑	↔	↔
32 Bit MCU	Infineon	10-97	↑	↔	↔	↔
	Microchip	4-18	↑	↑	↔	↑
	STMicro	40-52	↑	↔	↔	↔
	NXP	16-39	↑	↑	↔	↔
FPGA	Microsemi	12-30	↑	↑	↔	↑
	Efinix	19-36	↑	↑	↔	↑
USB	Infineon	12-16	↔	↑	↔	↑
	Microchip	6-16	↑	↑	↔	↑
Automotive	STMicro	40-52	↔	↔	↔	↔
	NXP	18-52	↑	↑	↔	↑
	Renesas	12-24	↔	↔	↔	↔
LCD's	Sharp	14-28	↔	↑	↔	↑
	WiseChip	14-16	↔	↔	↔	↔
	AZ Displays	14-18	↑	↑	↔	↑
SOM	Quectel	16-38	↑	↑	↔	↑
	Toradex	10-60	↑	↑	↔	↑

The logic and digital market faces tight supply conditions in October 2026, driven by edge AI, automotive ADAS, and industrial automation. Manufacturers like Texas Instruments, Microchip, and Renesas have updated portfolios for 8-bit and 32-bit microcontrollers, FPGAs, LCDs, and system-on-modules (SOMs), leading to extended lead times and allocation pressures.

BOOK A QUALIFIED MEETING. WIN THE FLORIDA EXPERIENCE. No purchase necessary · Rules on page 5

Electromechanical

Data as of November 2, 2026

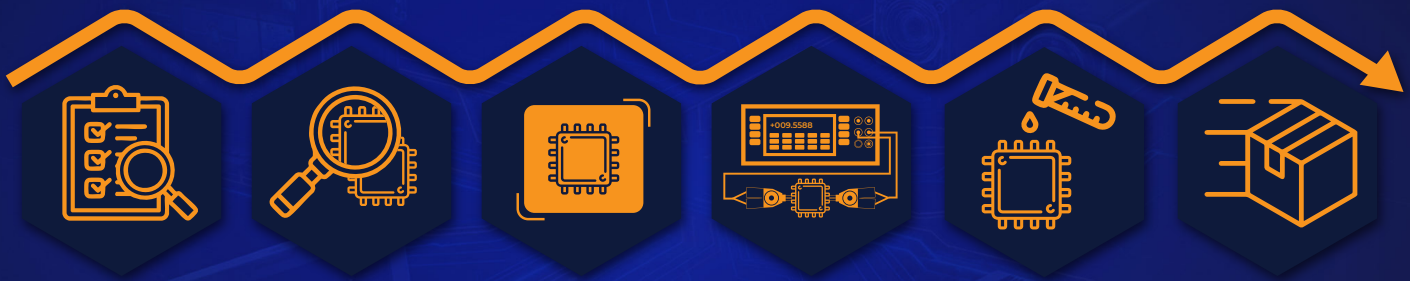
Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
Relays	TE Connectivity	18-20	↑	↔	↔	↑
	Panasonic	14-30	↑	↑	↔	↑
	Infineon	40-52	↔	↑	↔	↑
	American Zettler	16-30	↑	↔	↔	↑
Switches	Panasonic	10-12	↔	↔	↔	↔
	TE Connectivity	10-12	↔	↑	↔	↑
	ZF Electronics	18-20	↔	↑	↔	↑
	Grayhill	12-24	↑	↑	↔	↑
Timing	Microchip	12-52	↑	↑	↔	↑
	Kyocera	12-28	↔	↑	↔	↑
	Epson	12-24	↑	↔	↔	↑
	Abracon	12-30	↑	↑	↔	↑
Fans	SUNON	24-26	↔	↔	↔	↔
	Qualtek	20-24	↑	↑	↔	↑
	BOYD	12-14	↔	↔	↔	↔
	ADDA	20-24	↔	↔	↔	↔
Power Supplies (AC/DC)	CUI Inc.	14-28	↔	↑	↔	↑
	MEAN WELL	14-20	↑	↑	↔	↑
	Murata PS	14-44	↑	↑	↔	↑
	Recom	16-42	↑	↑	↔	↑
Power Supplies (DC/DC)	Murata PS	10-28	↑	↑	↔	↑
	Recom	15-24	↑	↑	↔	↑
	Wall Industries	8-10	↔	↔	↔	↔
	CUI Inc.	11-28	↔	↑	↔	↑
PCB Connector	TE Connectivity	12-22	↑	↔	↔	↑
	Amphenol	8-10	↔	↑	↔	↑
	Adam Tech	16-18	↔	↑	↔	↑
	JST	16-20	↑	↔	↔	↔

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
Lightning Connectors	Kyocera	10-12	↔	↑	↔	↑
	TE Connectivity	16-22	↑	↔	↔	↑
	WAGO	12-14	↔	↔	↔	↔
Terminal Blocks & Crimps	TE Connectivity	12-22	↑	↔	↔	↑
	METZ Connect	10-16	↔	↔	↔	↑
	Wieland Electric	12-16	↔	↑	↔	↑
	Major League Electronics	6-8	↔	↔	↔	↔

The electromechanical market faces strong demand driven by grid modernization and industrial automation. Manufacturers like Schneider Electric, TE Connectivity, and Omron focus on relays, switches, and fans. Surging raw material costs and supply constraints have pushed companies to adjust component pricing and manage extended lead times.

ASC GLOBAL

Counterfeit Detection



Incoming Inspection

External Visual Inspection

X-Ray / XRF

Electrical Testing

Chemical & Destructive Test

Repackaging & Shipping

- Quality Control Process for Every Order
- 2 Year Warranty on All Products
- Supply Chain Transparency

CERTIFICATIONS

AS 9120 | ISO 9001 | AS 6081

Price Action Tracker

Sixteen dated price rounds from nine suppliers have landed since February. Notices already covered elsewhere in this report are cross-referenced below the table rather than repeated.

Effective	Manufacturer	Scope	Reported change
Feb 1	**Analog Devices**	Portfolio-wide; includes backlog shipping after the date	~15% avg; up to 30% mil/high-rel
Feb 1	**Panasonic**	Tantalum capacitors	15 to 30%
Apr 1	**Texas Instruments**	Select analog and embedded	Up to 85% on individual parts
Apr 1	**NXP**	Part of portfolio	Not disclosed
Apr 1	**Infineon**	Power switches and related ICs	5 to 15%; higher on premium parts
Apr 1	**onsemi**	Certain products	Not disclosed
Apr 26	**STMicroelectronics**	Multiple lines; auto power, high-end MCUs	Not disclosed
Jun 1	**NXP**	Automotive, industrial, IoT	Not disclosed
Jun 28	**STMicroelectronics**	Microcontrollers	Not disclosed
Jul 1	**Texas Instruments**	Isolators, power-management ICs, MOSFETs	15 to 85% by part
Jul 1	**Infineon**	AI-server power, automotive power discretes	10 to 20%
Jul 1	**Yageo**	Entire capacitor portfolio, incl. MLCC to direct customers	Broadest in years; reports vary
Aug 14	**Microchip**	Selected products, all orders and shipments	Not disclosed
Aug 23	**STMicroelectronics**	Multiple lines; some auto MCUs already +15 to 20%	Not disclosed
Sep 13	**Analog Devices**	Commercial, industrial, military	Modest commercial; up to 30% military
Sep 28	**NXP**	Selected products	~10%, varies by part

Covered elsewhere in this report: Samsung Electro-Mechanics MLCC increases (pp. 7, 13), TI's Sept. 1 notice (p. 36), onsemi's Oct. 10 adjustment, Qualcomm's October increase, and Renesas on Jan. 1, 2027 (p. 37), and AMD from Dec. 27 (p. 40).

Patterns to Plan Around

- **Analog, power, and embedded move first.** Nearly every notice covers mature-node analog, power-management, power-switch, or MCU parts, where capacity has grown slowly while AI power delivery and EV platforms compete for the same lines.
- **Rounds repeat.** At least five suppliers have issued two or more rounds this year, so a spring quote has usually been superseded.
- **High-reliability grades carry the biggest percentages.** Military-qualified parts have seen up to 30% (ADI), and individual TI parts have been reported far above portfolio averages.

How Increases Compound

Starting price per 1,000 units	$100.00
After a 15% round	$115.00
After a further 10% round	$126.50

Two rounds of 15% and 10% add 26.5%, not 25%, because the second applies to the already-raised price.

Open-Order Exposure

Timing can matter more than the percentage. ADI's February round applied to backlog shipping on or after the effective date, so orders placed at the old price were invoiced at the new one. Ask suppliers to confirm in writing whether pricing follows order date or ship date, and to show base price, country of origin, and any surcharge as separate lines.

Sources: manufacturer customer notices as reported by TrendForce, EE Times China, and distributor channel sources, plus ASC Global research. Percentages are reported ranges across portfolios; individual parts can fall outside them. Confirm pricing part by part.

MADE BY ASC GLOBAL

MICROSD MANUFACTURING

DROP-IN REPLACEMENTS FOR INDUSTRIAL MICROSD



SLC / pSLC | MLC | TLC | QLC

Commercial	Industrial	SLC / pSLC
4GB - 1TB	**4GB - 512GB**	**512MB - 64GB**
TLC / QLC	MLC / TLC	High Write Endurance
0°C to +70°C	-40° to +85°C	-40° to +85°C
A1 / A2	Controlled BOM	Up to 100k P/E cycles
Cost Optimized for OEM	Long Lifecycle	SD and SPI Modes

10,000 insertion cycles • 36-month warranty

100% inspection • Up to 1.5M units/month

Industrial PCs & PLCs | HMIs | Surveillance | IoT & Smart Devices

Networking Equipment | Automotive Electronics | Medical Devices | Alarm & Security

Scan to Request

First Order in 3 Weeks

Manufacturing Capabilities

We source it, match it, or make it



When a part is allocated, discontinued, or simply gone, a drop-in replacement made to your specification can keep production moving. ASC Global builds storage and component solutions with engineering support, a locked bill of materials, and scheduled supply.

Industrial MicroSD

- Capacity: 512MB to 1TB
- Memory: SLC, pSLC, MLC, TLC, and QLC
- Temperature: -40°C to +85°C (industrial)
- Interfaces: SD and SPI
- Durability: up to 10,000 insertion cycles
- Warranty: 36 months, with a controlled BOM
- Capacity to build: up to 1.5M units a month
- First order: about 3 weeks

Custom SSDs

- Capacity: 64GB to 30TB
- Form factors: 2.5" SATA, M.2 SATA, M.2 NVMe, enterprise NVMe (U.2, U.3, E1.S)
- Performance: up to 6,800 MB/s sequential read and 1M random-read IOPS (NVMe)
- Endurance: up to 3 DWPD, high-endurance class
- Support: samples and qualification, fixed-BOM lifecycle, scheduled supply, and full traceability

How a Build Works

1 — Send your spec
A part number, datasheet, or requirement.

2 — Engineering review
We check fit, function, and specification.

3 — Free samples
Project samples for your qualification.

4 — Locked BOM
A controlled bill of materials for the program.

5 — Scheduled supply
Forecast-based builds, buffer stock, and 100% inspection.

ALSO MADE BY ASC

Fuses, circuit breakers, EMI filters, relays, resistors, thermistors, LED components, coin and cylindrical batteries, sensor components, diodes, and regulators, plus drop-in replacements.

SEND US YOUR SPEC.

quote@ascglobal.com | +1 954 718 2950

Free engineering samples, and a first MicroSD order in about three weeks.

Specifications are maximum ratings for the configurations noted and depend on the selected product and memory technology. Each ASC part number datasheet defines test method and endurance.

EXCESS INVENTORY SOLUTIONS

We Buy Excess Inventory in 24 Hours or Less

Turn surplus stock into cash, fast. We buy:

- DDR5, DDR4, DDR3, and DDR3L memory
- Power management ICs
- Analog and interface ICs
- Polymer tantalum capacitors
- Enterprise SSD and NAND
- Power MOSFETs and power stages
- High-capacitance MLCCs
- Polymer aluminum capacitors

Send your list to quote@ascglobal.com or call +1 954 718-2950 for further questions.



Consignment Terms

Offer Your Excess to Customers Worldwide

1

Share your list

Send part numbers, quantities, and date codes.

2

Agree on terms

We set consignment terms that fit your stock.

3

We do the rest

Our team lists, markets, and sells your parts to buyers worldwide.

Upload your list at www.ascglobal.com

ASC GLOBAL

End of Life (EOL)



Texas Instruments

Product	EOL	Notes
MC34063AP	Oct 2027	Replace with MC34063ADR. Not pin-to-pin (DIP to SOIC).
MC33063AD	Oct 2027	Replace with MC33063ADR. Pin-to-pin, same device on tape and reel.

Diodes Inc.

Product	EOL	Notes
ZXM61N02FTA	Apr 2027	Replace with DMN2053U-7.
ZXM61P03FTA	Apr 2027	Replace with DMP3165L-7.

onsemi

Product	EOL	Notes
NTZD0K4N021ZT1G	Jan 2027	Replace with NTZD3154NT1G.
NIV6350MT2TXG	Oct 2026	Replace with NIV6150MT2TXG.

NXP

Product	EOL	Notes
MFS2613AMDA2AD (FS26)	Dec 2027	Replace with MFS2613HMDA2AD, the eFS26 version, which NXP says is pin and software compatible.
MC33886PVW	Jan 2027	Replace with MC33HB2000AES. Last delivery was extended to January 2027.

Microchip

Product	EOL	Notes
TCN75-3.3MOA	Oct 2027	Replace with TCN75AVOA713.
HV9910CLG-G	Oct 2027	Replace with HV9910BLG-G or HV9961LG-G, both listed as pin-to-pin.



End of Life (EOL)

STMicroelectronics

Product	EOL	Notes
LSM6DSRXTR	Apr 2027	Replace with LSM6DSRTR.
TESEO-LIV3F	May 2027	ST lists no replacement. The part is being dropped for slow sales. Customers will need to qualify another GNSS module.

Infineon

Product	EOL	Notes
GS-065-011-1-L-TR (GaN)	Jun 2027	Replace with IGLR65R140D2. The package changes from PG-VSON-8 to PG-TSON-8.
GS-065-008-1-L-TR (GaN)	Jun 2027	Replace with IGLR65R200D2, also moving to PG-TSON-8.

Renesas

Product	EOL	Notes
932SQ420DGLF	Mar 2027	Replace with 932SQ420DKLF.
R1LP0408DSP-5SI#B1 (SRAM)	Dec 2028	Renesas points to another vendor's part, Infineon's CY62148G-45SXI.

Vishay

Product	EOL	Notes
VLRK31Q1R2-GS08 (PLCC2 LED)	Mar 2027	Replace with the new VLRK311 series. Vishay says form and fit are unchanged and electrical and optical specs are similar.
25YD22QT-R (Y-cap, T&R)	May 2027	Replace with 25YD22-R, the same 2200pF capacitor in bulk packaging.

ADI

Product	EOL	Notes
LT1580IT	Nov 2026	Replace with LT1580IT#PBF, the compatible lead-free version. The tin-lead version is ending because Carsem closed that line.
LT1763CS8-3.3	Nov 2026	Replace with LT1763CS8-3.3#PBF, the compatible lead-free version.



Authorized & Sourced Lines

Three ways ASC Global supplies your parts

Not every part should come through the same channel. ASC Global combines authorized lines, our own manufacturing, and an independent sourcing network, so you get the right route for each part number.

Authorized Lines

Western Digital
Authorized Reseller

HDDs, SSDs, NAS devices, and flash drives.

Diotec Semiconductor
Authorized Distributor

Diodes, transistors, integrated circuits, IGBTs, and MOSFETs.

Made by ASC

Industrial MicroSD
Drop-in replacements

For discontinued industrial cards.

Custom SSDs
Built to your spec

64GB to 30TB, locked BOM.

Drop-in Components
LED, fuses, and more

Equivalents for Kingbright, Cree LED, AMS OSRAM, Lite-On, Broadcom, Lumileds, Ledil, Luminus Devices, Mersen, Littelfuse, and Eaton/Bussmann parts.

Independent Sourcing

2,000+ Suppliers
Global network

Manufacturers and suppliers for allocated, obsolete, and hard-to-find parts.

Lab-Tested, Traceable
AS 6081, AS 9120, ISO 9001

Every open-market part goes through our lab.

Which Route Is Right?

You need new product from a brand we represent	Authorized lines
A discontinued part needs a drop-in replacement	Made by ASC
A part is allocated, obsolete, or hard to find	Independent sourcing

LOOKING FOR A SPECIFIC LINE? ASK US.

If we are not authorized, our sourcing network can still find it.

quote@ascglobal.com | +1 954 718 2950

Brand names belong to their owners. Drop-in replacement coverage lists the original brands our products are made to replace; it does not indicate authorization. Ask for our current authorized line list.

DDR3 and DDR4: Planning for the Memory Exit



Legacy Memory Is Becoming a Planning Risk

DDR3 and DDR4 remain essential to industrial equipment, including factory automation, medical devices, networking hardware, transportation systems, and embedded controllers. Unlike consumer electronics, many industrial systems remain in service for years, often outlasting the commercial availability of their original components.

As memory manufacturers prioritize newer technologies and AI-related demand, buyers must prepare for potential product discontinuations, reduced availability, and shorter last-time-buy (LTB) windows.
ASC Global's August 2026 semiconductor analysis highlighted how shifting production priorities and supply constraints are changing memory procurement requirements.

The challenge: Securing traceable, technically compatible memory for the remaining production and support lifecycle, not simply finding available stock.

Why Last-Time Buys Require More Planning

An end-of-life (EOL) notification can trigger a limited purchasing window. Delayed decisions expose manufacturers to price volatility, restricted inventory, and uncertain replenishment.

Legacy sourcing also introduces authenticity risks. Products from unverified channels may have incomplete traceability, incorrect labeling, undocumented handling, or a history of reuse. Counterfeit or improperly represented devices can cause failures that are difficult to diagnose after installation.

Before committing to a last-time buy, procurement teams should answer three questions:

- How long must the equipment remain in production and service?
- How much memory will manufacturing, repairs, and maintenance require?
- Are technically qualified alternatives available?

How to Calculate Your Last-Time Buy

A demand-based calculation helps balance supply continuity against excess inventory.

ILLUSTRATIVE OEM PLANNING EXAMPLE

Planning factor	Requirement
Annual production	1,200 systems
Support horizon	5 years
Memory per system	1 DDR4 module
Base demand	6,000 modules
Additional planning allowance	15%
Estimated LTB quantity	**6,900 modules**

Calculation: 1,200 systems × 5 years × 1 module × 1.15 = 6,900 modules.

The 15% allowance is an illustrative assumption, not a universal industry benchmark. Adjust the final quantity for existing stock, committed supply, repair demand, scrap rates, forecast uncertainty, minimum order quantities, storage conditions, and potential redesigns.

Avoid overbuying: Excessive LTB quantities can tie up working capital and leave manufacturers with inventory they cannot use.

Evaluate Alternatives Before Supply Ends

Potential replacement paths include pin-compatible devices, alternative module configurations, and redesigned assemblies using newer memory technologies.

However, identical pinouts do not guarantee compatibility. Engineering teams should verify:

- Voltage, timing, density, and module configuration.
- SPD settings, temperature ratings, and firmware compatibility.
- System-level performance and qualification requirements.

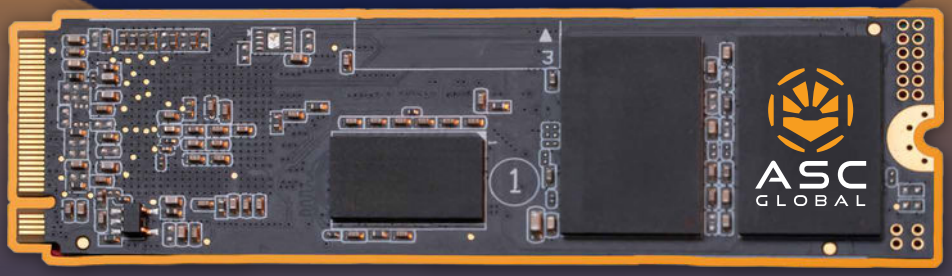
In some applications, replacing the complete memory module may be more practical than substituting individual components.

Where DDR4 stands now

Micron has ended DDR4 production. Samsung and SK hynix extended DDR4 output into 2026 because of strong pricing, but both are moving capacity to DDR5 and HBM. DDR3 is already in tight supply. If DDR4 is on your BOM, the time to plan a last-time buy is now.

MADE BY ASC GLOBAL

CUSTOM SSDs
BUILT TO YOUR SPEC



64GB to 30TB | OEM, embedded, industrial, and data center storage

2.5" SATA SSD	M.2 SATA SSD	M.2 NVMe SSD	Enterprise NVMe
SATA III 6 Gb/s	2242 / 2260 / 2280	2230 / 2242 / 2280	U.2 / U.3 / E1.S
Industrial PCs, appliances, server boot	Embedded systems and gateways	Edge computing, client and host systems	Cloud servers, virtualization, databases

6,800 MB/s
Max sequential read, NVMe

1M IOPS
Max random 4K read, NVMe

Up to 3 DWPD
Endurance, high-endurance class

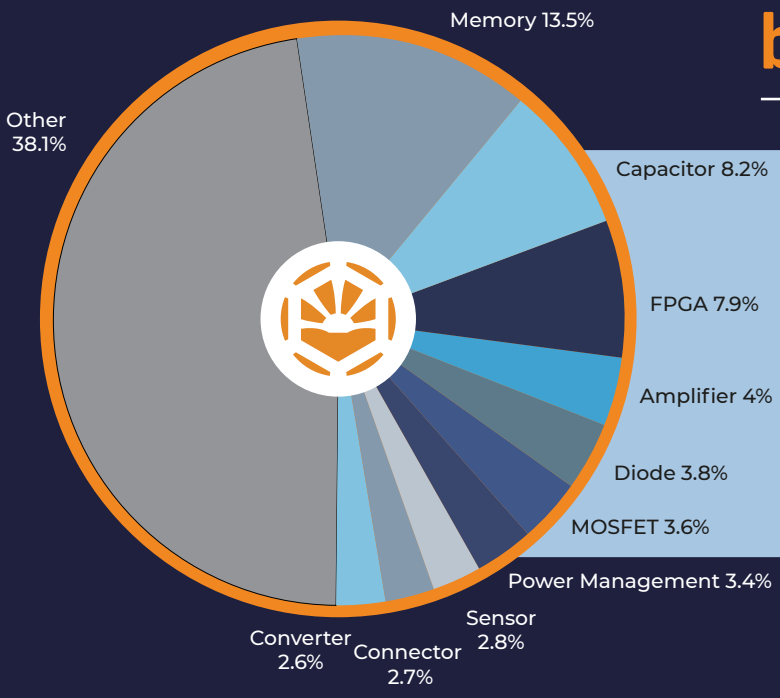
Maximum ratings. Values depend on configuration; each ASC part number datasheet defines test method and endurance.

Samples and qualification • Fixed-BOM lifecycle • Scheduled supply • Full traceability

SEND US YOUR SPEC.
quote@ascglobal.com

Test & Failure Rates

Test Rates by Device Type



Memory devices led testing at 13.5%, reflecting intense supply chain stress and allocation pressures. High testing volumes for capacitors and FPGAs highlight ongoing manufacturing constraints, while elevated activity in power management ICs, amplifiers, and discretes underscores widespread quality verification needs across critical electronic components amid volatile market conditions.

Top 10 Component Types by Failure Rate

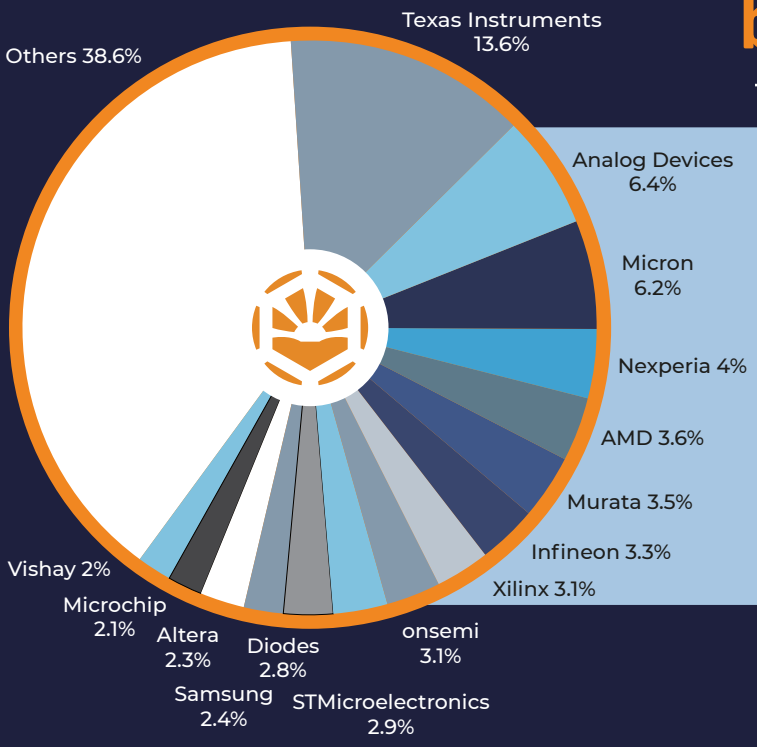
Here's a list of the top 10 device types most likely to fail our quality tests in September.

1. Microprocessor
2. Inductor, Coils, Chokes
3. Module
4. Transformer
5. Suppressor
6. Audio
7. Voltage Regulator
8. Modulator
9. System on a Chip (SoC)
10. DRAM

This ranking is determined by the proportion of failed results compared to the total units tested in each category. While some failures stem from aging or mishandling, others could indicate more serious quality issues or potential counterfeit threats.

BOOK A QUALIFIED MEETING. WIN THE FLORIDA EXPERIENCE. No purchase necessary · Rules on page 5

Test Rates by Manufacturer



Texas Instruments led testing submissions at 13.6%, followed by Analog and Micron. This distribution highlights strong demand across major global semiconductor brands. Sourcing patterns reveal distinct product structures, from Texas Instruments' power management focus to Micron's memory specialization, emphasizing that even established brands require rigorous batch verification in complex supply environments.

Top 10 Brands by Failure Rate In Open-Market Lots We Tested

Regarding manufacturer origin, these ten brands recorded the highest test failure rates in September. Failures reflect counterfeit, aged, or mishandled stock in the open market, not the manufacturer's production quality.

1. NICHIA
2. Everspin Technologies Inc.
3. Coilcraft
4. Monolithic Power Systems Inc.
5. Renesas
6. Atmel
7. Zilog
8. SK Hynix
9. IXYS
10. MACOM

This does not indicate widespread issues but suggests areas that may benefit from further supplier verification or risk mitigation measures.

ASC GLOBAL

ENVIRONMENTAL MANAGEMENT SYSTEM
ISO 14001 COMPLIANT

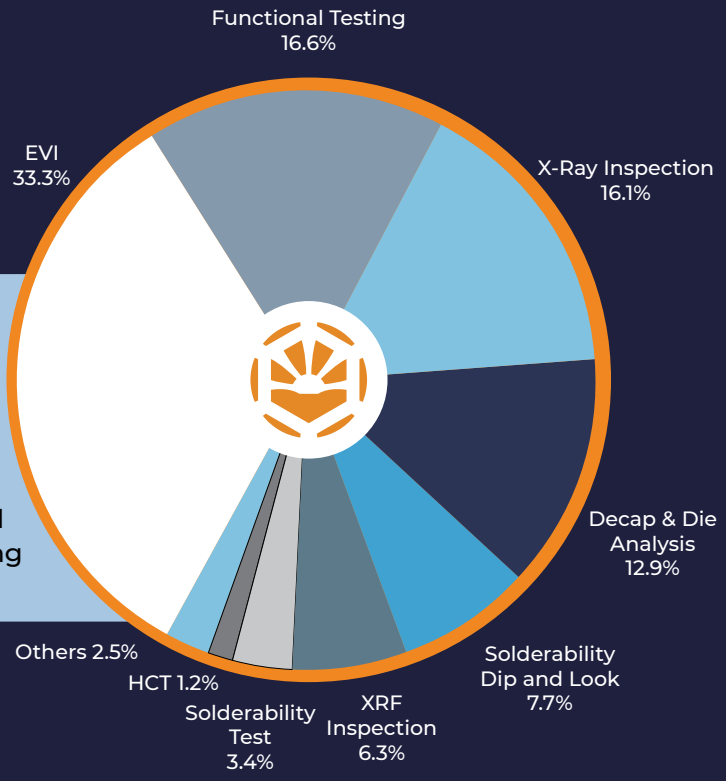
Driving Electronic Sustainability

- Energy-efficient operations
- Sustainable shipping practices
- Supply chain transparency
- Green sourcing

Test Types & Results

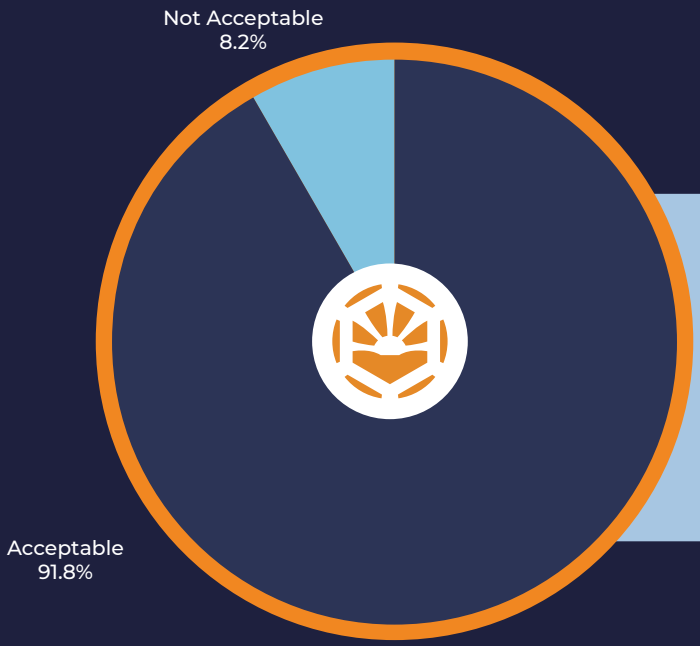
Test Types

External visual inspection led testing types at 33.3%, followed by functional testing at 16.6% and X-ray inspection at 16.1%. This diverse verification mix indicates that customers rely on multi-layered testing, including decap analysis and solderability checks, to mitigate counterfeit risks, detect internal defects, and ensure reliability across complex sourcing environments.



Test Results

Acceptable results reached 91.8%, while non-acceptable samples stood at 8.2%. This demonstrates a strong overall acceptance rate within a controlled range, indicating improved quality profiles. However, rigorous, multi-layered verification remains critical to mitigating counterfeit risks and ensuring long-term downstream reliability across complex supply chains.



Hot Commodities

Compiled from diverse sources, this data provides guidance. Treat it accordingly. For current availability on any part listed, send your part numbers to quote@ascglobal.com.

- Analog
- Power Products
- Passives
- Memory
- Logic & Digital
- Electromechanical

ASC's Picks

Type	Product #	Manufacturer	Lead Time weeks	Pricing Trend	Prognosis
	REF200AU	Texas Instruments	8-16	↑	↑
	ICM42688P	TDK	45	↑	↑
	MT25QU02GCBB8E120SIT	Micron	10-24	↑	↑
	STM32F405RGT6	STM	12-30	↑	↑
	MT41K256M16TW107P	Micron	40-53	↑	↑
	MT41K256M16TW107ITP	Micron	12-26	↑	↑
	LIS3DHTR	STM	16-24	↔	↑
	ADA4807-2ARMZ	Analog Devices	43-54	↔	↑
	ECMF02-4CMX8	STM	12-20	↑	↑
	MT41K128M16JT125ITK	Micron	20-30	↑	↑
	LMZM23601SILR	Texas Instruments	20-30	↔	↑
	KSZ8999I	Microchip	26-40	↑	↑

WHERE TO BUY

SHOP BY CATEGORY

Send us a part number or your full BOM. We source it, match it, or make it.

Memory & Storage

DDR5, DDR4, DDR3, and DDR3L · Enterprise SSD and NAND · HDDs, NAS, and flash drives

Power & Analog

Power management ICs · Power MOSFETs and power stages · Analog and interface ICs

Passives

High-capacitance MLCCs · Polymer tantalum and aluminum capacitors · Fuses, filters, relays, resistors

Logic & Digital

8-bit and 32-bit MCUs · FPGAs and timing devices · Interface ICs, LCDs, and SOMs

Electromechanical

Relays and switches · PCB connectors and terminal blocks · Power supplies and fans

MRO & Automation

New and surplus pneumatics, motion, hydraulics, HVAC, and electrical control · Aviation MRO

FOUR WAYS TO GET YOUR PARTS

ONLINE	Search billions of vetted parts with real-time stock at www.ascglobal.com
EMAIL	quote@ascglobal.com: send part numbers or a full BOM
PHONE	+1 954 718 2950, 24/7 support in 20+ languages
IN PERSON	electronica 2026, Munich: Hall B5, Stand 578

SCAN TO REQUEST A QUOTE

FREE MLCC RISK ASSESSMENT

Find the parts that could stop your line before a shortage does.

1 Send your list
Email your MLCC part numbers to quote@ascglobal.com.

2 We flag the risk
Lead times, allocation, and EOL exposure, part by part.

3 You decide early
Buffer stock, alternatives, or orders ahead of price moves.

Product Updates

Integrated Circuits

AI infrastructure continues reshaping semiconductor demand, with Samsung Electronics reporting a preliminary third-quarter 2026 operating profit of approximately $80.17 billion as AI-related memory demand tightens supply and raises component costs.

Competition in advanced silicon is intensifying as NVIDIA, AMD, and Broadcom target increasingly complex AI workloads. Buyers should monitor process-node availability, packaging capacity, allocation risks, and qualified alternatives when planning procurement.

FPGA

Altera began shipping post-quantum secure boot on Agilex 3 and 5 FPGAs on September 8. Lattice responded eight days later with the CNSA 2.0-ready Mach-N2. AMD has announced no equivalent.

Long product life is now a key buying factor. AMD lists 7 Series availability through 2040 and UltraScale+ through 2045. Altera now operates independently, owned 51% by Silver Lake and 49% by Intel.

Passives

Murata said it will discontinue some low-margin consumer GRM and automotive MLCCs. It will take orders until 2028 and ship through 2029 while moving capacity to AI server parts.

As Japanese and Korean makers cut consumer MLCC supply, Dell, HP, ASUS and Acer are qualifying Chinese suppliers such as Viiyong and Chaozhou Three-Circle. Quanta and Pegatron are also starting qualification.

eMMC

Smartphone brands are covering Q4 2026 builds from existing inventory, so eMMC/UFS orders are minimal. OEMs place only small volumes to keep supplier relationships, and TV and wearable makers resist higher prices.

The NAND supply base behind eMMC is shifting. YMTC has climbed to third in NAND bit shipments, ahead of Kioxia and Micron, and Micron expects its own NAND supply to grow more slowly than the industry's.

RDIMM

DRAM analysis found AI-server demand lifting high-capacity RDIMM orders while constrained supply drives contract prices upward; Samsung, SK hynix, and Micron are key suppliers to monitor closely.

DRAM prices will rise in fourth-quarter 2026 as cloud providers add server-memory orders; buyers should secure RDIMM allocations and validate module compatibility early to minimize disruptions.

Product Updates

SSD

Enterprise SSD contract prices are forecast to rise 23% to 28% QoQ in Q4 2026, the steepest of any memory category, as cloud providers buy high-capacity QLC drives for AI inference.

Cloud providers are moving to secure enterprise SSD supply through 2027. Micron says its PCIe Gen 5 and Gen 6 data center SSDs are shipping to leading customers for KV-cache applications.

HDD

HDD lead times are 50 weeks long as cloud providers lock in supply through 2027. Seagate and Western Digital are sold out for 2026, with key customers booked into 2028.

Toshiba plans to nearly double its high-capacity HDD output by fiscal 2027. Western Digital's 40TB UltraSMR drive is in customer qualification, and its HAMR roadmap targets 100TB and beyond.

Server CPU

AMD priced its 31-model EPYC 9006 "Venice" family from about $700 to $14,904. Reports say Venice capacity is booked through 2027, with some orders pushed into 2028.

Intel highlighted software approaches for running sandboxed agentic AI on Xeon CPUs, reinforcing processor demand for secure execution, orchestration, and enterprise AI workloads.

GPU

AMD has started HBM4 shipments for its MI455. CEO Lisa Su is seeking memory supply partnerships of three to five years with Samsung and SK hynix.

Nvidia's Vera Rubin is driving demand for HBM4. TSMC CoWoS packaging and HBM output, not GPU die yield, limit Nvidia's shipments, and these constraints are expected through at least H1 2027.

Motherboards

AM5 board list prices run from $259.99 for MSI's B850 Tomahawk Max WiFi II to $499.99 for Gigabyte's X870E Aero X3D Wood and $599.99 for ASUS's ROG Strix X870E-E.

Board demand depends on memory costs. Suppliers are shifting supply from PC DRAM to server DRAM, and PC buyers are resisting further price increases, which is pushing OEMs toward lower memory specifications.



Manufacturer Updates

SK Hynix

SK hynix has begun HBM4 volume shipments and has finished long-term supply negotiations with roughly ten customers. AMD CEO Lisa Su is seeking memory partnerships of three to five years with SK hynix and Samsung.

Samsung

Samsung and ASML expanded collaboration on High-NA EUV lithography and advanced photomask technology, targeting next-generation DRAM manufacturing to improve chip density, production efficiency, and semiconductor performance.

NXP

NXP partnered with Volkswagen to supply S32K5 microcontrollers for next-generation software-defined vehicles, supporting zonal architectures, consolidating vehicle functions, and reducing electronic control unit complexity.

Intel

Intel has raised CPU prices three times since late 2025, with high-end Panther Lake models up 15% to 20%. Those models pair GPU tiles made on TSMC's N3E process with compute tiles made on Intel's own 18A process.

Nvidia

Nvidia's Vera Rubin is driving HBM4 demand, and Nvidia is working with Google and Microsoft to make 800 VDC rack power an open industry standard. TSMC CoWoS packaging and HBM supply still limit Nvidia's shipments.

STMicroelectronics

STMicroelectronics has repriced three times in 2026, as has NXP. For buyers, how open orders are priced at shipment now matters more than the headline percentage.

Microchip Technology

Microchip closed its Hailo acquisition, adding edge AI and vision processors. It also partnered with Navitas on an 800V AI rack power design and added CNSA 2.0 post-quantum security support to its Flashtec PCIe Gen 5 SSD controller.

Infineon

Infineon completed its acquisition of C2i Semiconductors, whose team joins its Power Systems division. It is also expanding assembly and packaging in Thailand with a 48 billion baht investment, and launched a 27 kW three-phase power supply for AI servers.

Micron

Micron's 1-gamma DRAM and G9 NAND now lead its production, with the next generations due for volume production in 2H27. Its PCIe Gen 5 and Gen 6 data center SSDs are shipping to leading customers for KV-cache workloads.

Texas Instruments

Texas Instruments issued a notice on September 1 with product-specific adjustments and no single effective date. It is TI's second price change of 2026, so buyers need to confirm pricing part by part.

Manufacturer Updates

AMD

AMD is ramping its EPYC Venice processors on TSMC's 2nm process. CEO Lisa Su says AMD will substantially increase supply in 2027 with partners including TSMC, and AMD may also adjust some CPU prices.

TSMC

TSMC is expected to raise 2027 prices by 5% to 10% for advanced nodes, 10% to 15% for advanced packaging, and 3% to 5% for mature nodes.

Lattice

Lattice partnered with Arm on secure management platforms for AI servers. It also launched Sentry v5.0, which it calls the first firmware resilience stack with post-quantum cryptography, ahead of its OCP Global Summit demos.

Amphenol

Amphenol named Ryan Fisher to lead its Harsh Environment Solutions division, with Luc Walter moving to strategic programs in January 2027.

Skyworks

Skyworks completed its merger with Qorvo on October 5, and Qorvo was delisted from Nasdaq. Qorvo's business now operates as Qorvo Technologies, LLC, a Skyworks subsidiary. The deal combines two of the largest RF front-end suppliers.

Qualcomm

Qualcomm raised prices on its Snapdragon X and X2 Elite PC processors by about 10% starting in October, as more advanced nodes and packaging add to its costs.

Onsemi

Onsemi's broad price adjustment took effect October 10. The notice does not say how existing orders will be treated, so orders shipping after that date may carry the new pricing.

Renesas

Renesas raises prices again on January 1, 2027, the latest effective date among recent notices from Texas Instruments, Analog Devices, Allegro and onsemi. That leaves buyers a short window to place orders at current pricing.

Vishay

Vishay released SOT-227 power modules with 650 V superjunction MOSFETs that can be used without redesigning the circuit board.

GlobalFoundries

GlobalFoundries signed a multi-year $2 billion agreement to make silicon interposers for TSMC's CoWoS packaging at its Malta, New York fab. It also announced a new FD-SOI platform for Physical AI chips, with production in Germany starting in 2028.



Earnings Recap

Automotive

Toyota Motor Corp.

- Revenue: $84.50B
- Net Income: $9.20B
- Net margin: 10.9%
- Revenue YoY: +10.4%

General Motors

- Revenue: $48.03B
- Net Income: $1.31B
- Net margin: 2.7%
- Revenue YoY: +1.9%

Ford Motor Company

- Revenue: $48.30B
- Net Income: -$1.33B
- Net margin: -2.7%
- Revenue YoY: -3.8%

The automotive industry faces uneven profitability as manufacturers navigate pricing pressure, tariffs, supply-chain disruptions, and shifting demand. Toyota delivered revenue and net income gains, supported by favorable currency effects and hybrid demand. General Motors increased sales modestly, while Ford's revenue declined and restructuring charges drove a net loss, highlighting execution risks.

AI and Data Center

Microsoft Corp.

- Revenue: $90.00B
- Net Income: $35.76B
- Net margin: 39.7%
- Revenue YoY: +18%

NVIDIA Corp.

- Revenue: $96.22B
- Net Income: $59.68B
- Net margin: 62.0%
- Revenue YoY: +106%

Alphabet Inc.

- Revenue: $119.79B
- Net Income: $40.77B
- Net margin: 34.0%
- Revenue YoY: +25%

AI infrastructure demand is accelerating as enterprises and cloud providers expand spending on GPUs, hyperscale data centers, networking, and cloud services. NVIDIA benefits from accelerated computing demand, while Microsoft and Alphabet monetize AI through cloud platforms and software. Rising capital expenditures, power availability, cooling requirements, and investment returns remain major challenges.

Earnings Recap

Automation Industry

Siemens AG
- Revenue: $24.2B
- Net Income: $3.0B
- Net margin: 14.4%
- Revenue YoY: +7%

ABB Ltd
- Revenue: $9.47B
- Net Income: $1.23B
- Net margin: 13.0%
- Revenue YoY: +14%

Rockwell Automation
- Revenue: $2.31B
- Net Income: $0.40B
- Net margin: 17.6%
- Revenue YoY: +7.9%

The automation industry is benefiting from demand for industrial AI, smart manufacturing, robotics, digitalization, and energy-efficient infrastructure. Siemens reported higher revenue and net income, ABB strengthened its performance through electrification and automation demand, and Rockwell Automation improved profitability. Companies continue prioritizing productivity, operational resilience, software integration, and connected industrial systems.

Consumer and Personal Computing

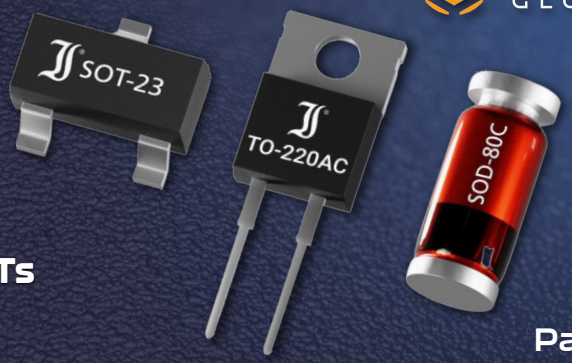
LG Electronics
- Revenue: $17.72B
- Net Income: $526.8M
- Net margin: 2.97%
- Revenue YoY: +8.9%

HP Inc.
- Revenue: $15.70B
- Net Income: $0.66B
- Net margin: 4.2%
- Revenue YoY: +12.5%

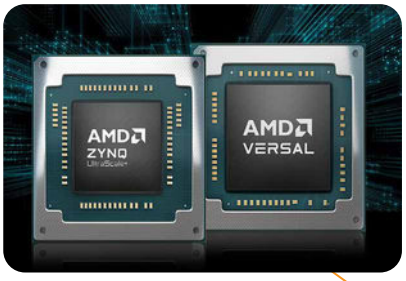
Lenovo Group
- Revenue: $26.94B
- Net Income: -$0.61B
- Net margin: -2.3%
- Revenue YoY: +43.0%

Consumer and personal computing demand is shifting toward AI-enabled PCs, premium devices, and integrated ecosystems. LG Electronics grew revenue 8.9% on a margin under 3%, HP increased revenue 12.5% despite declining PC shipments, and Lenovo grew sales 43% alongside a statutory loss. Rising memory costs, component supply constraints, pricing adjustments, and replacement cycles continue shaping industry profitability and competition.

Diotec Semiconductor | Authorized Distributor
We have availability on
- Diodes
- Transistors
- Integrated Circuits
- IGBTs
- MOSFETs



Industry Updates



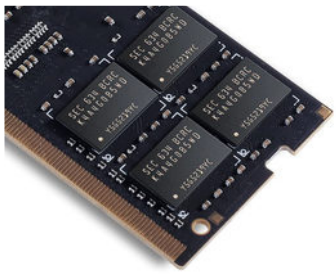
AMD Announces 2027 Price Adjustments

AMD will adjust prices for FPGAs, adaptive SoCs, embedded x86 processors, System-on-Modules, and accelerator cards amid rising semiconductor manufacturing, materials, packaging, and logistics costs. New pricing applies to shipments on or after December 27, 2026.

US Packaging Capacity Expands

GlobalFoundries signed a five-year, $2 billion agreement with TSMC to manufacture silicon interposers at its Malta, New York facility. The US supply will support TSMC's CoWoS advanced-packaging ecosystem for high-performance computing and AI systems, with volume production ramping in 2028.





Memory Costs Reshape Devices

Strong demand for AI infrastructure and high-bandwidth memory is lifting DRAM prices. September reporting described rising memory prices affecting smartphones, laptops, consoles, and other devices, pushing manufacturers toward price increases, lower specifications, redesigns, or longer product replacement cycles through 2027.

Infineon Unveils Server Supply

Infineon introduced a 27-kilowatt three-phase power-supply reference design for AI servers using 800VDC or ±400VDC architectures. Combining CoolSiC, CoolMOS, sensors, gate drivers, and microcontrollers, it achieves peak efficiency above 98% and supports Open Rack V3 requirements for next-generation data centers.



Industry Updates

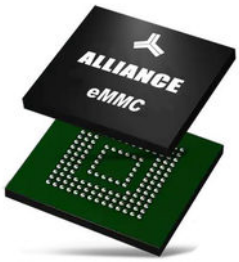


OmniVision Launches Industrial Sensor

OMNIVISION announced the OG12S10, a 12-megapixel global-shutter CMOS sensor for factory automation and transportation. It supports exposures as short as one microsecond, near-infrared imaging, and 75 frames per second, with sampling planned for November 2026 and production scheduled for Q4.

Alliance Expands eMMC Capacity

Alliance Memory expanded its industrial eMMC portfolio to 512GB, adding 64GB, 128GB, 256GB, and 512GB options. Devices support eMMC 5.1, operate from minus 40°C to 85°C, and target embedded systems requiring higher-capacity onboard storage across industrial applications and automotive systems.





TDK Expands Predictive Maintenance

TDK SensEI's edgeRX Starter predictive-maintenance system is now available through distribution. Each package includes ten vibration and temperature sensors, a gateway, and six months of software, combining edge processing and cloud analytics to flag equipment anomalies in industrial machinery and conveyors.

Microchip Acquires VORAGO Technology

Microchip acquired VORAGO Technologies' radiation-hardened microcontroller and processor technology, adding its HARDSIL process and engineering team. The portfolio supports aerospace, defense, space, and extreme-temperature industrial applications, potentially helping developers improve radiation tolerance and reduce design time for devices and systems.



Earnings Signals

What chipmakers and the distribution channel are reporting, and what it means for your Q4 orders.

Distribution Channel

- Two of the largest global electronics distributors reported sales up roughly 40 to 48% year over year
- Book-to-bill above parity in all regions, with backlog building into the first half of 2027
- Lead times up in most categories; price gains led by memory
- Price inflation at about one-third of sequential component growth

Texas Instruments (Q3)

- Revenue +28% YoY; gross margin 64%
- Analog pricing up in 2H after a flat 1H
- Lead times ticking up from roughly 13 weeks
- Equipment lead times, not floor space, limit capacity
- Q4 guide: $5.8 to 6.3B; 2027 talks add supply-assurance pricing

STMicro & Infineon

- ST Q2 revenue: $3.49B, +26% YoY
- Infineon FQ3 revenue: EUR 3.70B, +9% in constant currency
- Infineon segment margin 18%; full-year guide raised to high teens
- Infineon cites strong AI power and automotive demand

Samsung Electro-Mechanics

- Q2 revenue: KRW 3.46T, +24.2% YoY
- Operating profit: KRW 440.4B, +106.7%
- AI MLCC long-term agreements with 10+ customers

What This Means for Q4

Distributors report book-to-bill above parity and backlog into 2027, and price inflation is now a visible share of growth. Analog makers have moved from flat to rising prices, and TI says equipment lead times are slowing new capacity. Order against confirmed forecasts rather than spot inquiries.

Need the parts behind these numbers? Ask ASC Global.

Order online at www.ascglobal.com or visit Hall B5, Stand 578.

quote@ascglobal.com

+1 954 718 2950

Sources: company earnings releases and calls (distributor results reported in August 2026; Texas Instruments Q3, Oct. 21), TrendForce, and company reports for STMicroelectronics, Infineon, and Samsung Electro-Mechanics.

Industries We Cover

Components and support for long-lifecycle, high-reliability programs

Our customers build equipment that has to run for years. That is why we pair component supply with traceability, testing, and end-of-life planning, not just availability.

Aerospace & Defense

Traceable, lab-tested parts under AS 9120 and AS 6081 counterfeit-avoidance processes, plus end-of-life and obsolescence support.

Automotive

Power, microcontroller, and passive components, with EOL alternatives and last-time-buy planning for long production runs.

Aviation

Aviation components and MRO supplies for aftermarket programs, with documentation you can trace.

Communications

Networking, interface, and timing ICs and passives for telecom and enterprise equipment.

Consumer Electronics

Memory, power, and passive components for high-volume builds, with help when allocation hits.

Data Centers

Server memory, enterprise storage, power, and passives, sourced even when allocation tightens.

Energy

Power semiconductors, protection, and control parts for new energy, grid, and power-supply equipment.

Industrial

Industrial automation, MRO, and embedded components, plus MicroSD and drop-in replacements for long-lived equipment.

Medical

Traceable components for long-lifecycle medical devices, with test reports and EOL planning.

Also serving: marine, power supply, lighting, telecommunications, home appliances, security protection, and networking.

TELL US YOUR INDUSTRY AND YOUR PART NUMBERS.

We match you with the right route: authorized line, drop-in replacement, or sourcing.

quote@ascglobal.com
+1 954 718 2950

DISCLAIMER

ASC Global's Marketing & Data Analysis Team prepared this report for information only, drawing on our team's expertise and publicly available information. While we work to ensure accuracy, ASC Global cannot warrant the completeness, timeliness, or accuracy of the analyses, which may include forward-looking statements, assumptions, or opinions that can change without notice. This report is not financial, investment, or business advice; do your own research before making decisions. ASC Global is not responsible for losses or damages resulting from the use of this information. This report is the property of ASC Global, and unauthorized reproduction or distribution is prohibited. Certification scope (AS 9120, AS 6081, ISO 9001) applies to ASC Global's quality processes.

Hard to Find?
Not for Us.

We source it, match it, or make it.

Send us a part number

INDUSTRIES SERVED

- Aerospace & Defense
- Automotive
- Aviation
- Communications
- Consumer Electronics
- Data Centers
- Energy
- Industrial
- Medical

Shortage and Allocation Sourcing

Industrial MicroSD Manufacturing

EOL and Obsolescence Solutions

LOCATIONS

Global presence with responsive customer service.
9 offices strategically placed in major regions of the global electronic economy.



United States Headquarters
7880 N University Dr. Ste. 100
Tamarac, FL 33321

EUROPE
United Kingdom
Poland
Germany
Italy
Hungary

CHINA
Shenzhen
Hong Kong

MEXICO
Guadalajara, Jalisco

Your Reliable Supplier for Electronic Components

Offering Global Sourcing & Manufacturing

Send your part numbers today.

AS 9120 | ISO 9001 | AS 6081 certified

+1 954 718 2950
quote@ascglobal.com
www.ascglobal.com